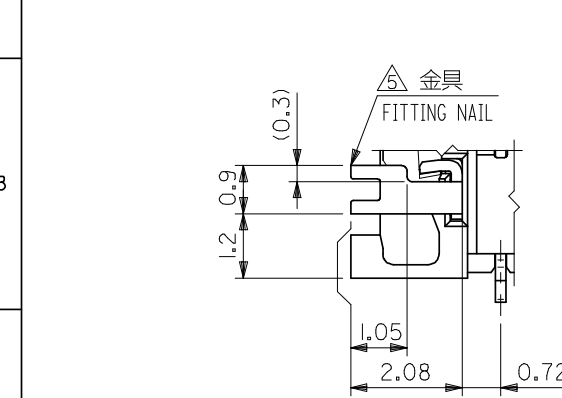
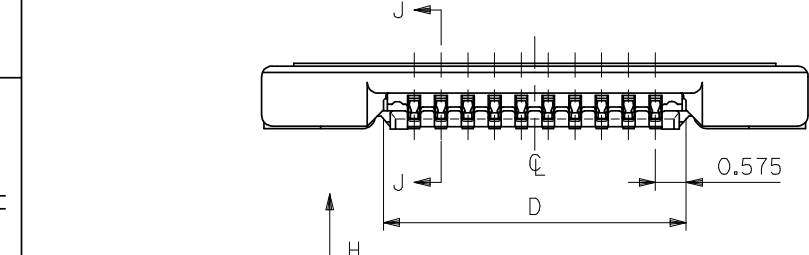
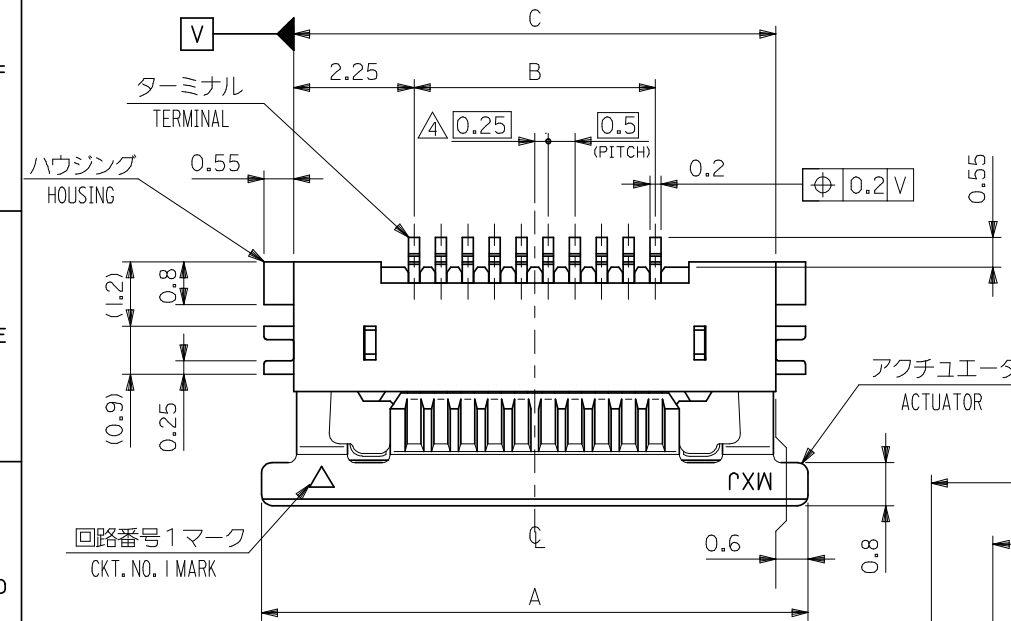
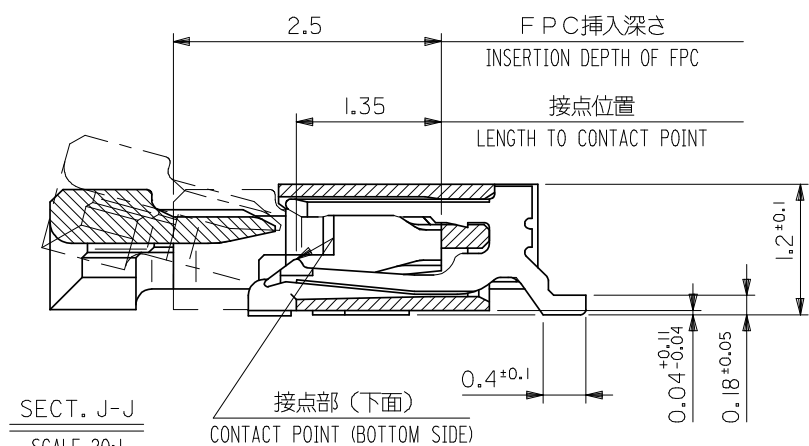
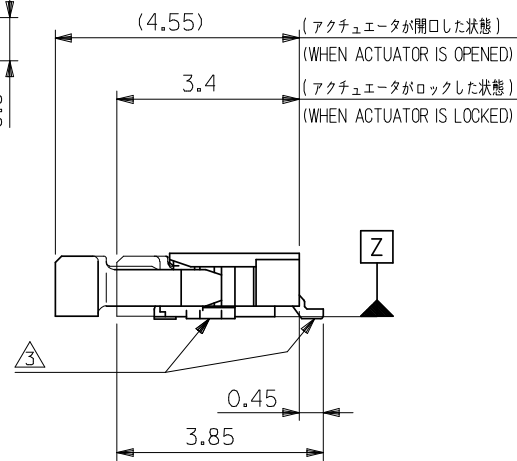




VIEW H



SECT. J-J
SCALE 20:1



0.28±0.03	13.65	17.0	12.5	18.2	54548-2671	54548-2629	26
	12.65	16.0	11.5	17.2	54548-2471	54548-2429	24
	12.15	15.5	11.0	16.7	54548-2371	54548-2329	23
	11.65	15.0	10.5	16.2	54548-2271	54548-2229	22
	11.15	14.5	10.0	15.7	54548-2171	54548-2129	21
	10.65	14.0	9.5	15.2	54548-2071	54548-2029	20
	10.15	13.5	9.0	14.7	54548-1971	54548-1929	19
	9.65	13.0	8.5	14.2	54548-1871	54548-1829	18
	9.15	12.5	8.0	13.7	54548-1771	54548-1729	17
	8.65	12.0	7.5	13.2	54548-1671	54548-1629	16
	8.15	11.5	7.0	12.7	54548-1571	54548-1529	15
	7.65	11.0	6.5	12.2	54548-1471	54548-1429	14
	7.15	10.5	6.0	11.7	54548-1371	54548-1329	13
	6.65	10.0	5.5	11.2	54548-1271	54548-1229	12
0.3±0.03	6.15	9.5	5.0	10.7	54548-1171	54548-1129	11
	5.65	9.0	4.5	10.2	54548-1071	54548-1029	10
	5.15	8.5	4.0	9.7	54548-0971	54548-0929	9
	4.65	8.0	3.5	9.2	54548-0871	54548-0829	8
	4.15	7.5	3.0	8.7	54548-0771	54548-0729	7
	3.65	7.0	2.5	8.2	54548-0671	54548-0629	6
	3.15	6.5	2.0	7.7	54548-0571	54548-0529	5
	2.65	6.0	1.5	7.2	54548-0471	54548-0429	4
					EMBOSSD TAPE	製品番号	極数
	FPC THICKNESS	D	C	B	A	ORDER No. オータ番号	MATERIAL No. Ckt+

REVISED EC NO: J2008-4048 DRWN:WABEI CHKD:THARUYAMA APPR:NUKITA	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
		10 UNDER	±0.2	DRAWN BY HSHIMABUKURO	DATE '04/02/10	0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT -LEAD FREE-					
		10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE '04/02/10						
		30 OVER	±0.3	APPROVED BY MSASAO	DATE '04/02/10	MOLEX INCORPORATED					
		ANGULAR	±3 °	MATERIAL NO.	DOCUMENT NO.						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-54548-039		SHEET NO. 1 OF 2			

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

F

E

D

C

B

A

F

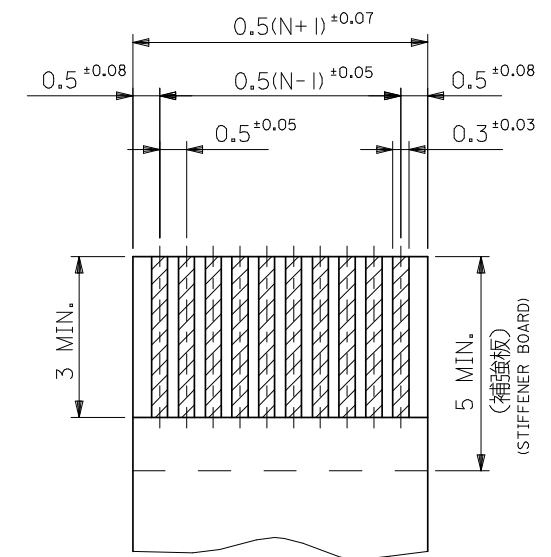
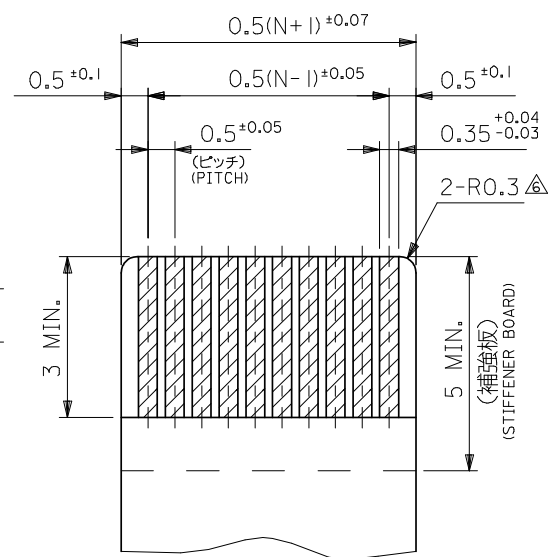
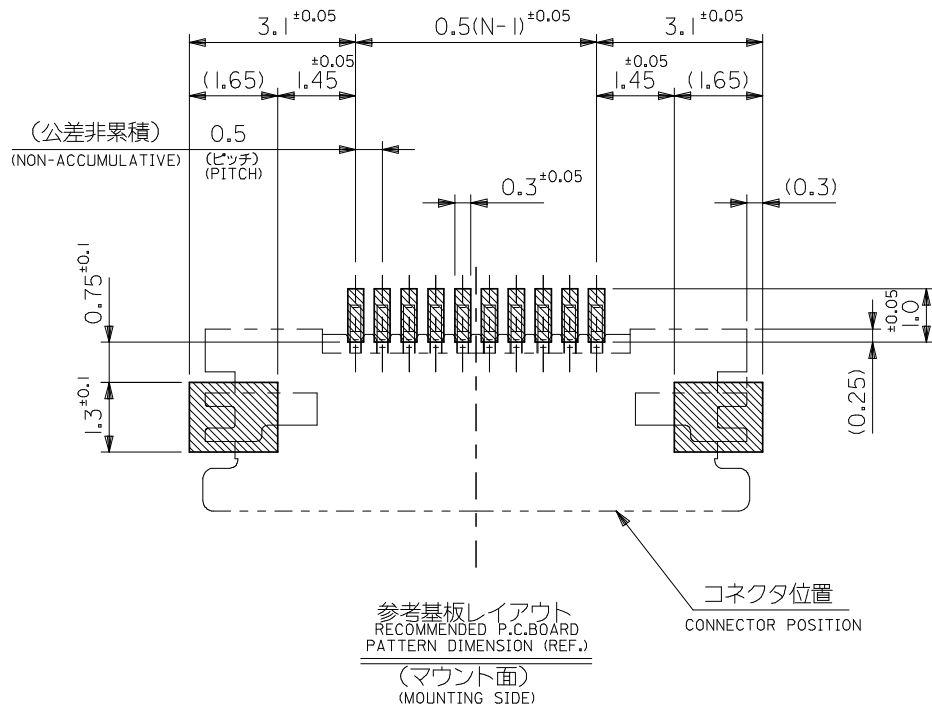
E

D

C

B

A



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 表参照)
(THICKNESS: SEE CHART)

適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 表参照)
(THICKNESS: SEE CHART)

注記 NOTES

I. 使用材料 MATERIAL

- ハウジング : LCP, UL94V-0
HOUSING
アクチュエータ : PPS, UL94V-0
ACTUATOR
ターミナル : リン青銅 (t=0.2)
TERMINAL PHOSPOR BRONZE
メッキ : 接点部: 金メッキ
PLATING CONTACT PORTION : GOLD PLATING
テール部: 鍍メッキ
SOLDERING PORTION : TIN OVER PLATING
下地: ニッケルメッキ
UNDER PLATING: NICKEL PLATING
金具 : リン青銅、鍍メッキ (t=0.2)
FITTING NAIL PHOSPOR BRONZE, TIN PLATING
下地: ニッケルメッキ
UNDER PLATING: NICKEL PLATING

- △ パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING
OF P.C.B. PATTERN.
△ R0.3はFPC導体部にかからないこと
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.
7. 本製品は54548-**-21の鉛フリー(部分金メッキ)品である。
THIS PRODUCT IS LEAD FREE OF 54548-**-21 (SELECTIVE GOLD).
8. N: 極数 N: CIRCUIT.

2. エンボステープ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO. 54548-**-29 SHOULD BE LOCKED.
△ ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 Z
に対し上方向 0 MAX.、下方向 0.15 MAX. とし
相互のバツキ量は 0.1 MAX. とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM Z
UPPER DIRECTION: 0 MAX., LOWER DIRECTION: 0.15 MAX.
OFFSET BETWEEN UPPER AND LOWER 0.1 MAX.
△ 偶数極に適用。
APPLY FOR EVEN CIRCUIT.

FPC/FFC について:

打ち抜き方向は導体側から補強板側を推奨します。
導体部については軟銅箔35μmまたは50μmを推奨します。

ABOUT FPC/FFC

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED CONDUCTOR SPEC :
THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER.

FPC について:

補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。

ABOUT FPC

RECOMMENDED MATERIAL/THICKNESS.
STIFFENER FILM : POLYIMIDE
BASE FILM THICKNESS : 25μm
BONDING AGENT : THERMOSETTING BONDING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON THE CONTACT
AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN
ELECTRICAL CONTINUITY.

REVISED EC NO: J2008-4048 DRWN:WABEI CHKD:THARUYAMA APPR:NUKITA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	20 THIRD ANGLE PROJECTION	MODEL NO.	
		10 UNDER	±0.2	DRAWN BY HSHIMABUKURO	DATE '04/02/10	TITLE 0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT -LEAD FREE-				
		10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE '04/02/10					
		30 OVER	±0.3	APPROVED BY MSASAO	DATE '04/02/10	molex MOLEX INCORPORATED				
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.				SHEET NO.
	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		SD-54548-039				2 OF 2
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										

